AMENDMENTS TO THE CLAIMS

1. (cancelled)

2. (currently amended) A dynamically modular processing unit as recited in claim 14, wherein the first interchangeable~~dynamic~~ back plane includes one or more data manipulating systems, and wherein the first interchangeable~~dynamic~~ back plane is coupled to the first optimized circuit board.

3. (original) A dynamically modular processing unit as recited in claim 2, wherein the first optimized circuit board includes a plurality of segments, wherein the plurality of segments are interconnected.

4. (original) A dynamically modular processing unit as recited in claim 3, wherein the plurality of segments are interconnected in a layered circuit board configuration.

5. (previously presented) A dynamically modular processing unit as recited in claim 14, wherein one or more peripherals external to the first non-peripheral based encasement are selectively connected to the first bus system.

6. (original) A dynamically modular processing unit as recited in claim 5, wherein the one or more peripherals external to the first non-peripheral based encasement include at least one of:

(i) a mass storage device;

(ii) a peripheral input device;

(iii) a peripheral output device;

(iv) a network interface;

(v) a second dynamically modular processing unit;

(vi) a proprietary input connection;

(vii) a proprietary output connection; and

(viii) a proprietary device.

7. (currently amended) A dynamically modular processing unit as recited in claim 6, wherein the second dynamically modular processing unit comprises:

a second non-peripheral based encasement;

a second processor coupled to a second optimized circuit board that includes a second bus system, wherein the second optimized circuit board is coupled to the second non-peripheral based encasement; and

a second interchangeable ~~dynamic~~ back plane coupled to the second non-peripheral based encasement, wherein the second interchangeable ~~dynamic~~ back plane provides flexibility and support to peripherals and applications.

8. (original) A dynamically modular processing unit as recited in claim 7, wherein the first bus system and the second bus system are directly coupled to form a single bus system for an enterprise having the dynamically modular processing units.

9. (original) A dynamically modular processing unit as recited in claim 8, wherein the combination of the dynamically modular processing units provide increased processing power to the enterprise.

10. (previously presented) A dynamically modular processing unit as recited in claim 14, further comprising memory coupled to the first bus system and within the non-peripheral based encasement.

11. (previously presented) A dynamically modular processing unit as recited in claim 14, wherein the dynamically modular processing unit provides a processing platform that is employed in association with any electrical enterprise.

12. (currently amended) A dynamically modular processing unit as recited in claim 14, wherein the first interchangeable ~~dynamic~~ back plane includes one or more data manipulating systems, and wherein a modification of the one or more data manipulating systems alters an application of the dynamically modular processing unit.

13. (previously presented) A dynamically modular processing unit as recited in claim 14, further comprising a cooling system, wherein the cooling system comprises a thermodynamic cooling process.

14. (currently amended) A dynamically modular processing unit comprising:

a first non-peripheral based encasement;

a first processor coupled to a first optimized circuit board that includes a first bus system, wherein the first optimized circuit board is a tri-board electrical printed circuit board configuration removably secured within ~~coupled to~~ the first non-peripheral based encasement; and

a first interchangeable ~~dynamic~~ back plane coupled to the first non-peripheral based encasement, wherein the first interchangeable ~~dynamic~~ back plane provides flexibility and support to peripherals and applications, and wherein the dynamically modular processing unit is configured to provide processing versatility through selective coupling to one or more other dynamically modular processing units in an enterprise, wherein all of the dynamically modular processing units are interconnected at the system bus level.

15. (currently amended) A dynamically modular processing unit as recited in claim 14, wherein the first interchangeable ~~dynamic~~ back plane is selectively exchangeable with another interchangeable ~~dynamic~~ back plane, and wherein the logic of the first interchangeable ~~dynamic~~ back plane is different from the another interchangeable ~~dynamic~~ back plane.

16. (previously presented) A dynamically modular processing unit as recited in claim 14, wherein the dynamically modular processing unit is employed in one of (i) a central processing unit, and (ii) an electronic consumer device.

17. (previously presented) A dynamically modular processing unit as recited in claim 14, wherein the dynamically modular processing unit is a handheld computer device.

18. (original) A dynamically modular processing unit as recited in claim 17, wherein the handheld computer device is selectively coupled to at least one of (i) a peripheral input device, and (ii) a peripheral output device.

19. (original) A dynamically modular processing unit as recited in claim 18, wherein the peripheral input device and the peripheral output device do not include processing power, and wherein the peripheral input device and the peripheral output device in combination with the dynamically modular processing unit forms a laptop computer device.

20. (previously presented) A dynamically modular processing unit as recited in claim 14, wherein the dynamically modular processing unit is used as a smart electronic consumer device.

21. (cancelled)

22. (cancelled)

23. (cancelled)

24. (cancelled)

25. (cancelled)

26. (previously presented) A modular processing system comprising:

a first non-peripheral based encasement having first, second and third side wall supports and first and second end plates removably coupled to the first non-peripheral based encasement and comprising a plurality of ventilation ports;

a first processor coupled to a first optimized circuit board that includes a first bus system, wherein the first optimized circuit board is coupled to the first non-peripheral based encasement, wherein the first optimized circuit board is a tri-board electrical printed circuit board configuration removably secured within the first non-peripheral based encasement; and

a first interchangeable back plane coupled to the first non-peripheral based encasement, wherein the first interchangeable back plane provides flexibility and support to peripherals and applications.

27. (previously presented) A modular processing system as recited in claim 26, wherein one or more peripherals external to the first non-peripheral based encasement are selectively connected to the first bus system.

28. (original) A modular processing system as recited in claim 27, wherein the one or more peripherals external to the first non-peripheral based encasement include at least one of:

(i) a mass storage device;

(ii) a peripheral input device;

(iii) a peripheral output device;

(iv) a network interface;

(v) a second dynamically modular processing unit;

(vi) a proprietary input connection;

(vii) a proprietary output connection; and

(viii) a proprietary device.

29. (currently amended) A modular processing system as recited in claim 28, wherein the second dynamically modular processing unit comprises:

a second non-peripheral based encasement;

a second processor coupled to a second optimized circuit board that includes a second bus system, wherein the second optimized circuit board is coupled to the second non-peripheral based encasement; and

a second interchangeable ~~dynamic~~ back plane coupled to the second non-peripheral based encasement, wherein the second interchangeable ~~dynamic~~ back plane provides flexibility and support to peripherals and applications.

30. (previously presented) A modular processing system as recited in claim 29, wherein the first bus system and the second bus system are coupled to form a single bus system.